2-3-1-4 SR 挟まれ傷/SR 的夹伤/Pinch mark on solder resist

【特徴】SR表面に幅広く複数の傷状剥離が見られ る状態の欠陥

【特征】在SR表面可见大面积的多处剥落伤痕的缺陷。

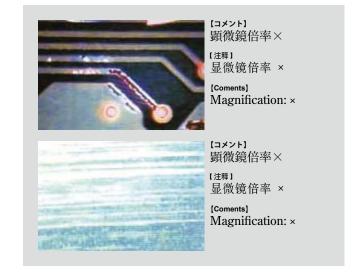
[Characteristics] Multiple scratch-like stripping is observed on the solder resist surface.

【原因・判断ポイント・発生工程】SR塗布乾燥後 コンベア搬送中に重なり、装置内に挟まって出来た もの(SR塗布乾燥後の洗浄工程)

【原因、判断要点、发生工序】SR 涂布烘干后在输送 过程叠板,被夹在装置内而发生的(SR 烘干后的清 洗工序)。

[Causes/processes involved/keys to judgment]

Solder resist coated boards are piled and pinched in the machine during transportation on a conveyor to cause the defect (Cleaning process after solder resist application)



2-3-1-5 SR レベラ傷/ SR 在热风整平时的划伤 / Scratch on solder resist by HAL

【特徴】SRの表面にSRの剥離を伴う傷が存在し、 SR剥離部にはんだの付着が見られる状態の欠陥

【特征】SR 表面随着剥落而划伤, SR 的剥离部位又 附着焊料的缺陷。

[Characteristics] Scratched and peeled portion of solder resist exists on the board surface and solder is attached to the peeled area.

【原因・判断ポイント・発生工程】HAL工程で基 板の反りなどによりHALガイドに接触して出来た もの(HAL工程)

【原因、判断要点、发生工序】在 HAL 工序,由于 板件翘曲等接触 HAL 导板而引起的 (HAL 工序)。

[Causes/processes involved/keys to judgment]

The defect is caused by the contact of the HAL guide with solder resist due to the board warping in the HAL process (HAL process)

